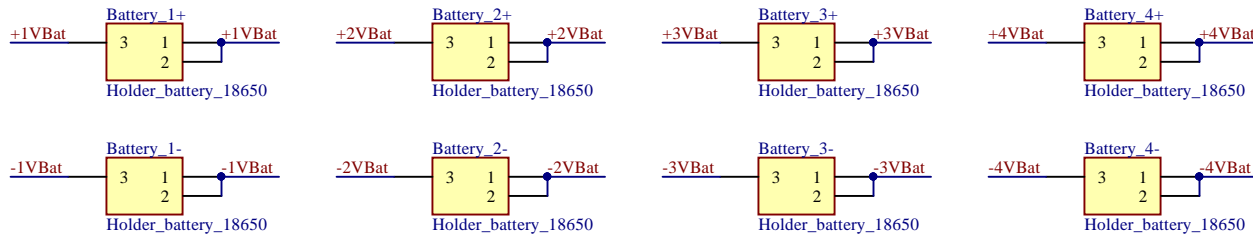
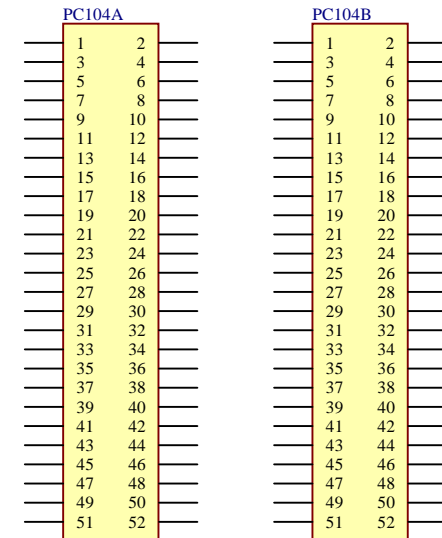


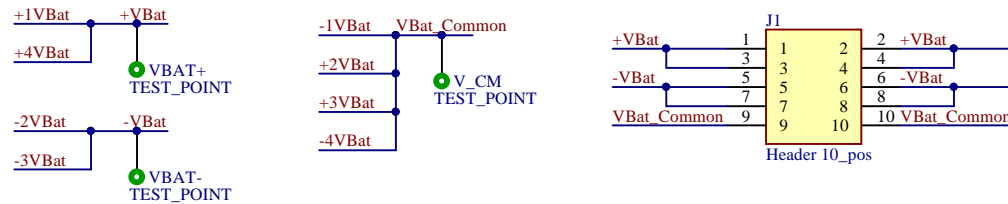
BATTERIES' CONNECTORS



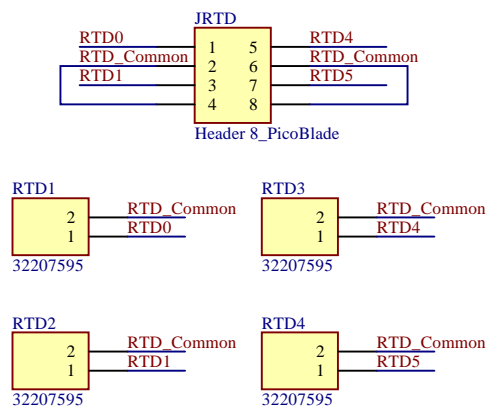
PC104 CONNECTIONS



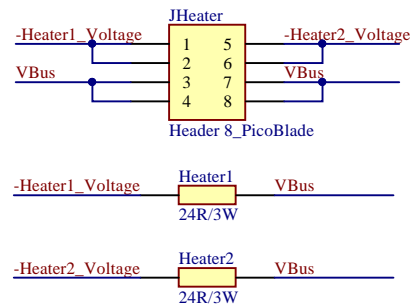
BATTERY CONNECTIONS



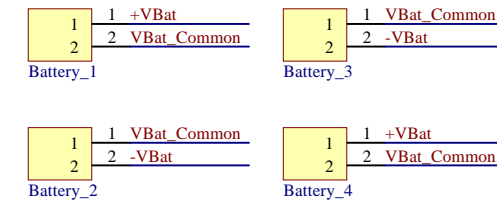
RTD SENSORS CONNECTIONS



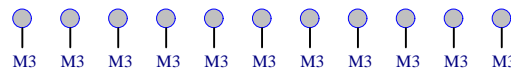
HEATER CONNECTION



BATTERIES' PADS



MECHANICAL HOLES



SpaceLab - Federal University of Santa Catarina

Project: bat2_project.prjpcb / [No Variations]

Title: Battery Board

Designed by: Amanda Batista Medeiros

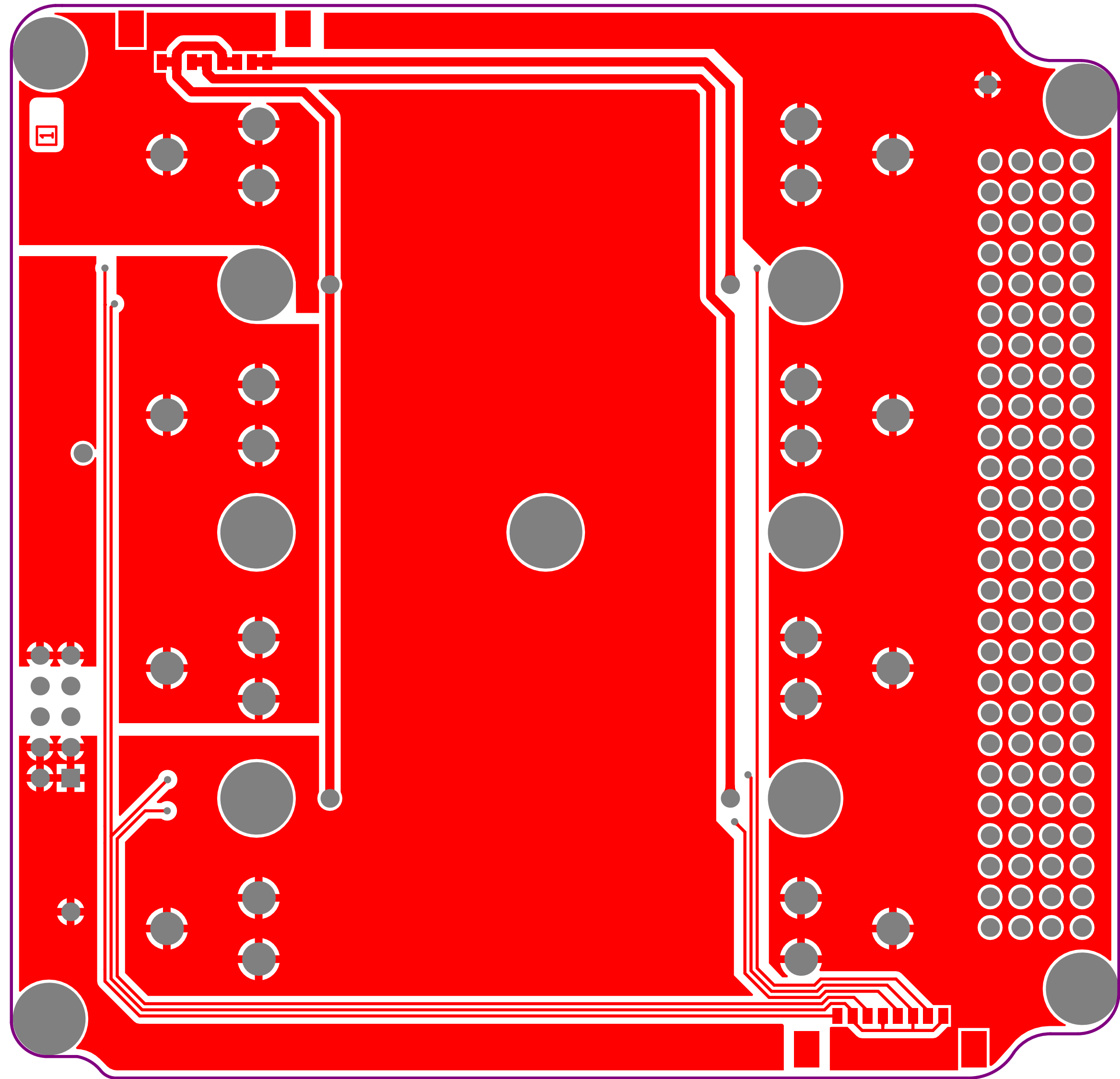
Date: 28/09/2020

Version: v0.0

Sheet 1 of 1

Size: A4





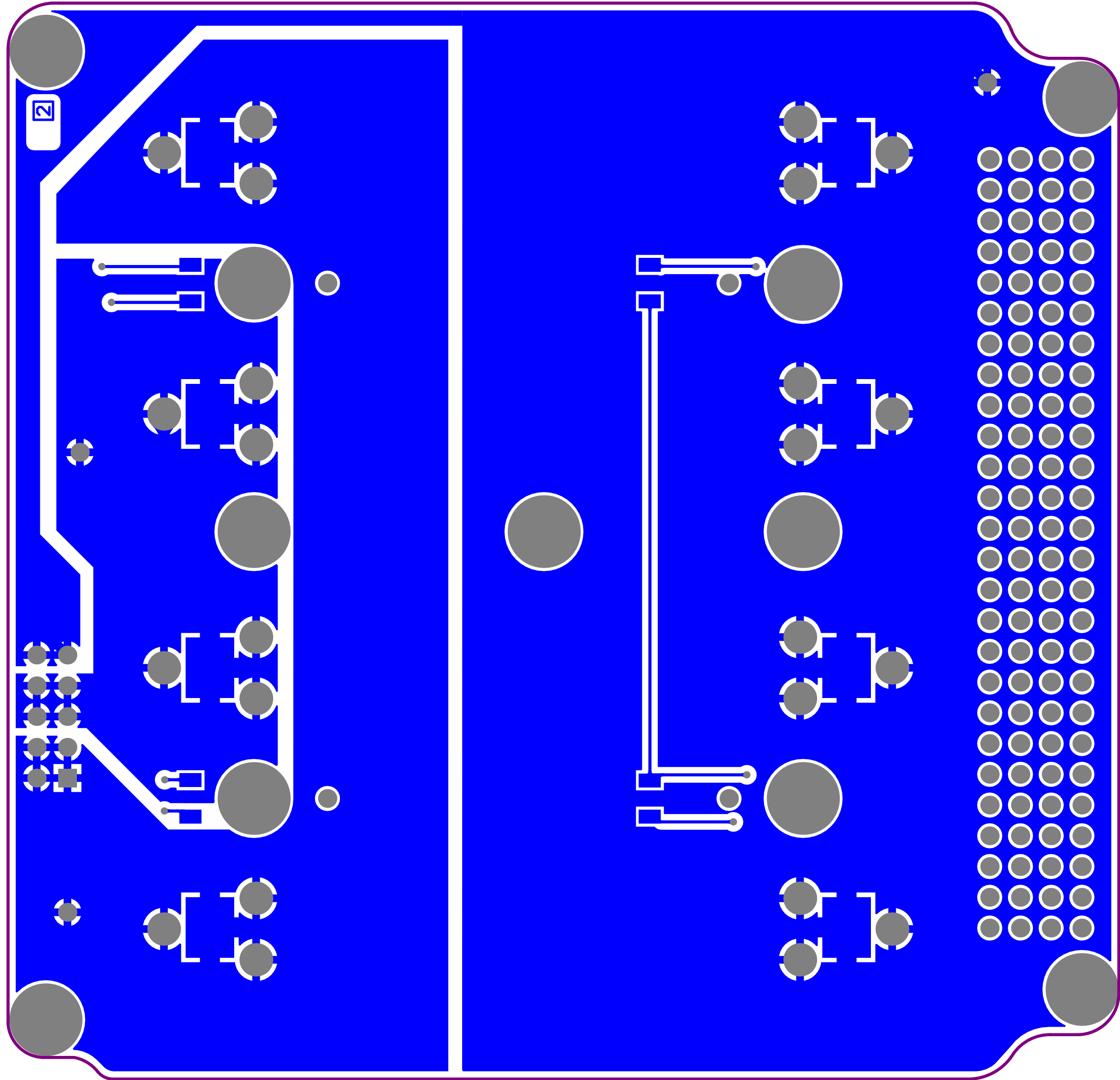
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



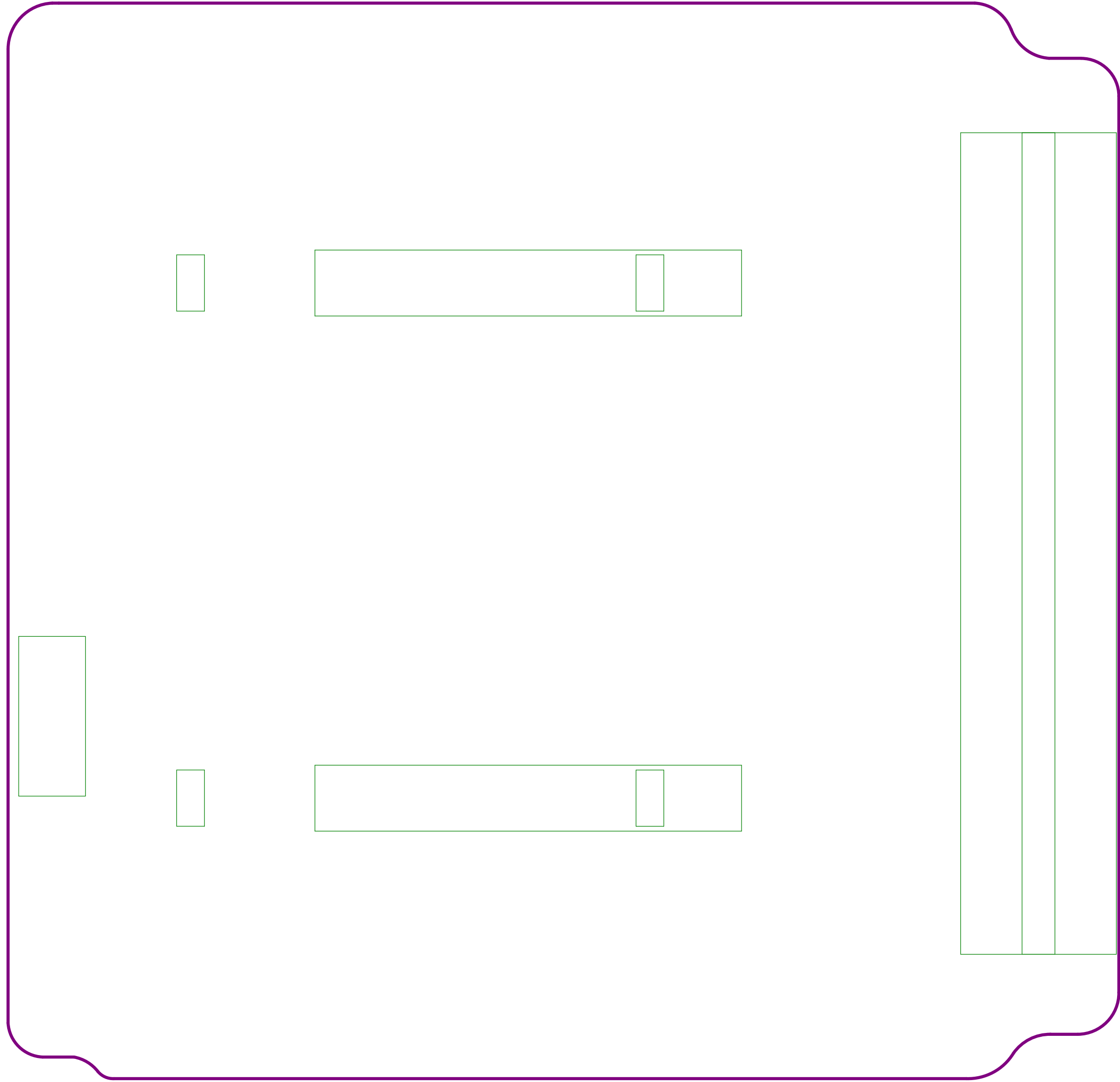
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom availible
- Check BOM for not placed components



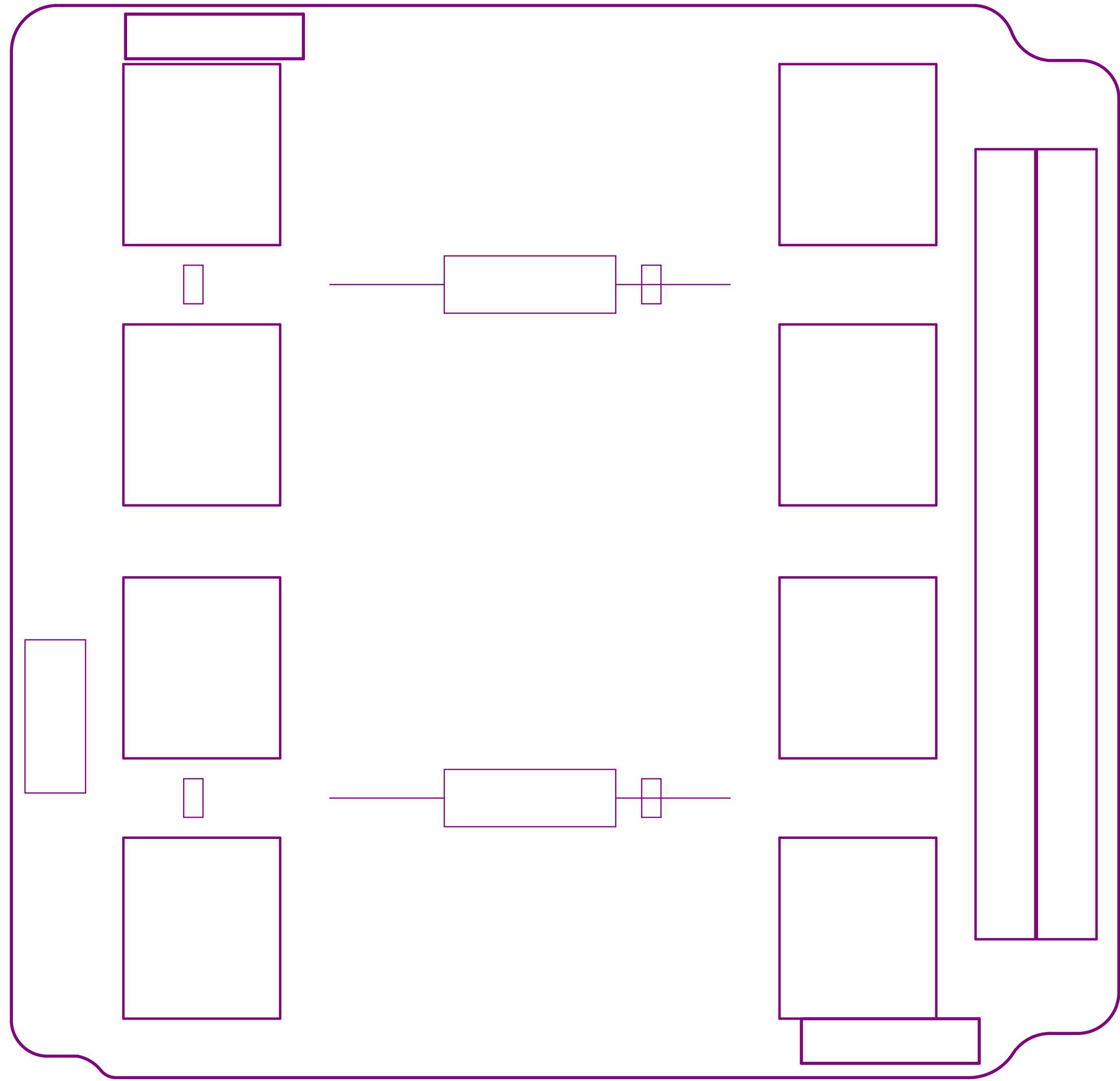
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4—Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack—up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric Core	FR-4	1,500mm	4,2	
5	Bottom Layer	Copper	0,035mm		
6	Bottom Solder	Solder Resist	0,010mm	3,5	
7	Bottom Overlay				

Fabrication specifications:

- Copper base 10Z:
 - PCB Material: Prepeg FR4–Standard
 - PCB Tickness: 1.6mm
 - PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
 - Soldermask Color: Green
 - Vias: Force Complete Tenting
 - Special: Stack–up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

